



11N40

Power MOSFET

400 V N-CHANNEL MOSFET

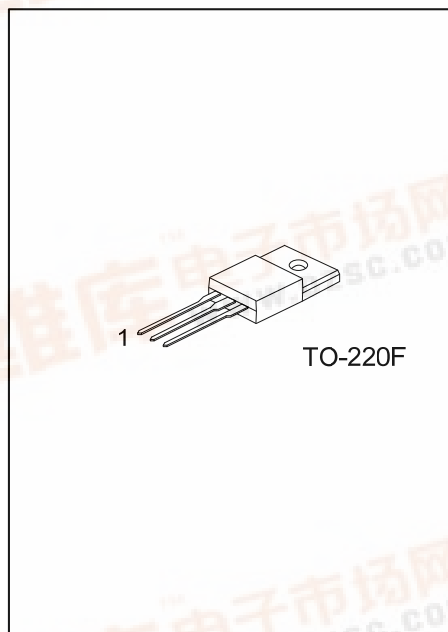
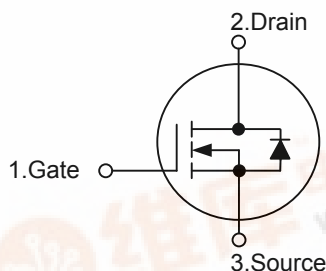
DESCRIPTION

The **11N40** uses UTC's advanced proprietary, planar stripe, DMOS technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with low gate voltages. This device is suitable for use as a load switch or in PWM applications.

FEATURES

- * $R_{DS(ON)} = 0.48\Omega$ @ $V_{GS} = 10\text{ V}$
- * Ultra low gate charge (typical 27 nC)
- * Low reverse transfer capacitance ($C_{RSS} =$ typical 20 pF)
- * Fast switching capability
- * Avalanche energy specified
- * Improved dv/dt capability, high ruggedness

SYMBOL



Lead-free: 11N40L

Halogen-free: 11N40G

ORDERING INFORMATION

Ordering Number			Package	Pin Assignment			Packing
Normal	Lead Free Plating	Halogen Free		1	2	3	
11N40-TF3-T	11N40L-TF3-T	11N40G-TF3-T	TO-220F	G	D	S	Tube

11N40L-TF3-T	(1)Packing Type	(1) T: Tube
	(2)Package Type	(2) TF3: TO-220F
	(3)Lead Plating	(3) G: Halogen Free, L: Lead Free, Blank: Pb/Sn



■ ABSOLUTE MAXIMUM RATING ($T_C = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V _{DSS}	400	V
Gate-Source Voltage		V _{GSS}	±30	V
Continuous Drain Current (T _C = 25°C)		I _D	11.4	A
Pulsed Drain Current (Note 1)		I _{DM}	46	A
Avalanche Current (Note 1)		I _{AR}	11.4	A
Avalanche Energy	Single Pulsed(Note 2)	E _{AS}	520	mJ
	Repetitive(Note 1)	E _{AR}	14.7	
Peak Diode Recovery dv/dt (Note 3)		dv/dt	4.5	V/ns
Power Dissipation		P _D	147	W
Derate above 25°C			1.18	W/°C
Junction Temperature		T _J	150	°C
Storage Temperature		T _{STG}	-55 ~ +150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■ THERMAL DATA

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT
Junction-to- Ambient	θ_{JA}			62.5	$^\circ\text{C}/\text{W}$
Junction-to-Case	θ_{JC}			0.85	$^\circ\text{C}/\text{W}$

■ ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0 V, I _D =250 μA	400			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =400V, V _{GS} =0 V			1	μA
		V _{DS} =320V, T _C =125°C			10	
Gate-Body Leakage Current	I _{GSS}	V _{DS} =0 V, V _{GS} = ±30 V			±100	nA
Breakdown Voltage Temperature Coefficient	ΔBV _{DSS} /ΔT _J	I _D =250 μA, Referenced to25°C		0.42		mV/°C
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250 μA	2.0		4.0	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 5.7 A		0.38	0.48	Ω
DYNAMIC PARAMETERS						
Input Capacitance	C _{ISS}	V _{DS} =25V, V _{GS} =0V, f=1MHz		1100	1400	pF
Output Capacitance	C _{OSS}			180	240	
Reverse Transfer Capacitance	C _{RSS}			20	30	
SWITCHING PARAMETERS						
Turn-ON Delay Time	t _{D(ON)}	V _{DD} =200V, I _D =11.4A, R _{GEN} =25Ω(Note 4,5)		30	70	ns
Turn-ON Rise Time	t _R			100	210	
Turn-OFF Delay Time	t _{D(OFF)}			60	130	
Turn-OFF Fall-Time	t _F			60	130	
Total Gate Charge	Q _G	V _{DS} =320V, V _{GS} =10V, I _D =11.4A (Note 4,5)		27	35	nC
Gate Source Charge	Q _{GS}			7.3		
Gate Drain Charge	Q _{GD}			12.3		

■ ELECTRICAL CHARACTERISTICS(Cont.)

SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Drain-Source Diode Forward Voltage	V_{SD}	$I_S=11.4\text{ A}, V_{GS}=0\text{ V}$			1.5	V
Maximum Continuous Drain-Source Diode Forward Current	I_S				11.4	A
Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}				46	
Reverse Recovery Time	t_{RR}	$V_{GS} = 0\text{ V}, di_F/dt = 100\text{ A/s},$		240		ns
Reverse Recovery Charge	Q_{RR}	$I_S = 11.4\text{ A (Note 4)}$		1.8		μC

- Note
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
 2. $L=7\text{ mH}$, $I_{AS}=11.4\text{ A}$, $V_{DD}=50\text{ V}$, $R_G=25\Omega$, Satarting $T_J=25^\circ\text{C}$.
 3. $I_{SD} \leq 11.4\text{ A}$, $di/dt \leq 200\text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Satarting $T_J=25^\circ\text{C}$.
 4. Pulse Test: Pulse Width $\leq 300\text{ s}$, Duty Cycle $\leq 2\%$.
 5. Independent of operating temperature.

■ TEST CIRCUIT

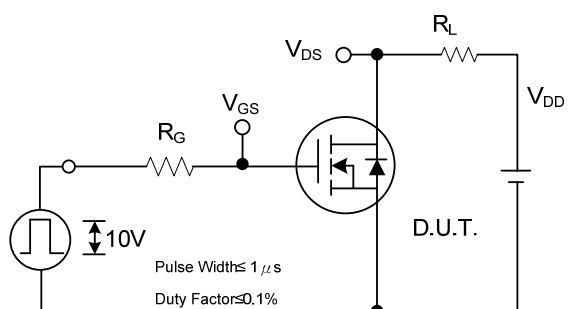


Fig. 2A Switching Test Circuit

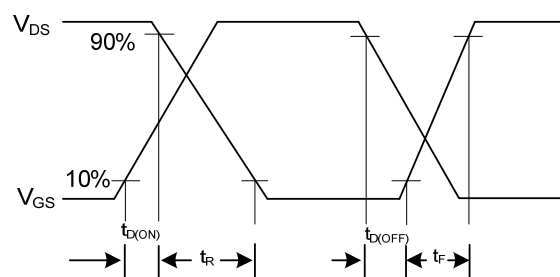


Fig. 2B Switching Waveforms

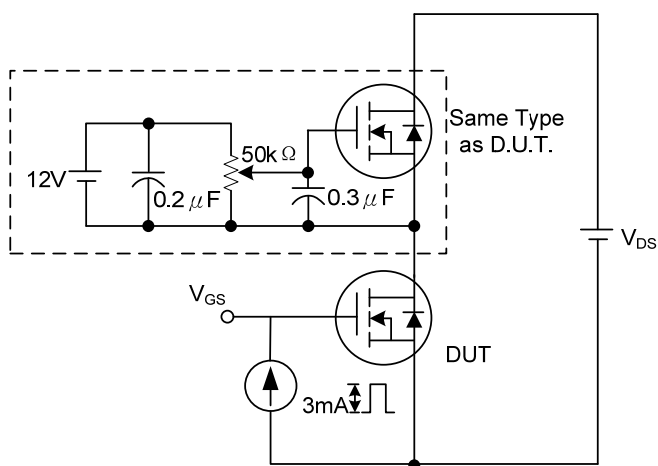


Fig. 3A Gate Charge Test Circuit

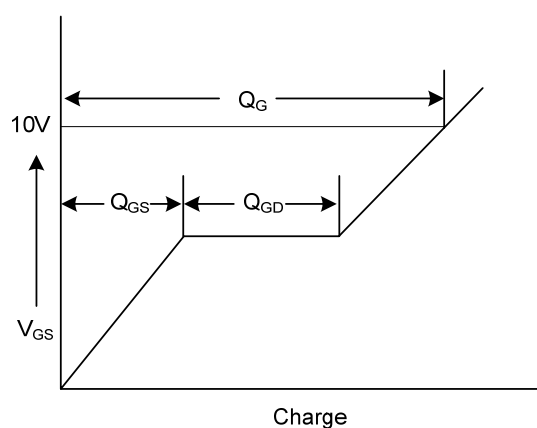


Fig. 3B Gate Charge Waveform

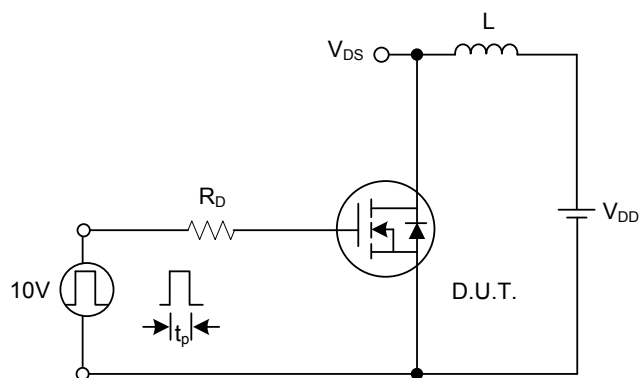


Fig. 4A Unclamped Inductive Switching Test Circuit

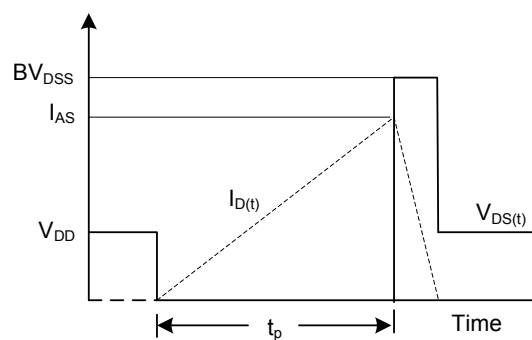


Fig. 4B Unclamped Inductive Switching Waveforms

■ TEST CIRCUIT(Cont.)

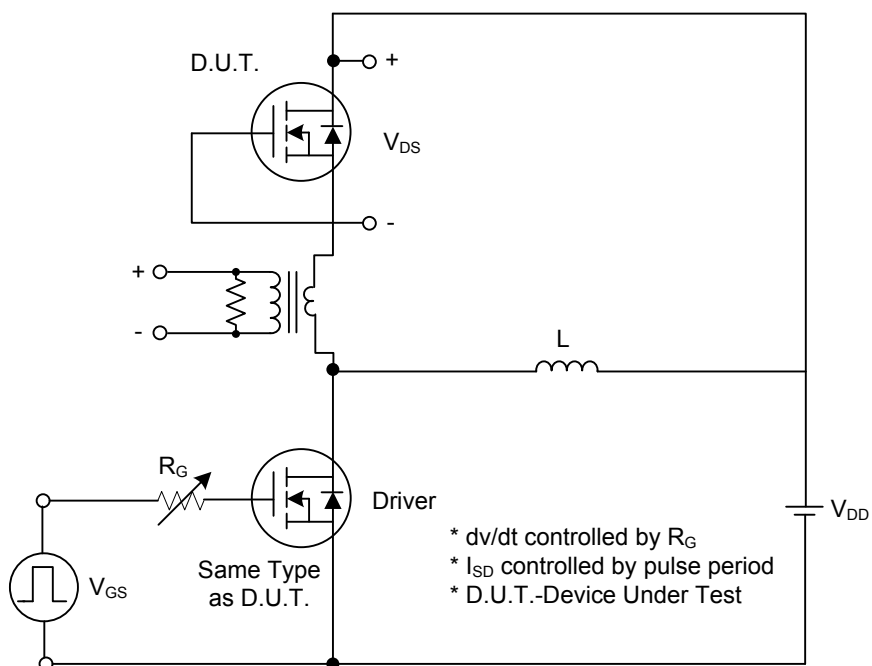
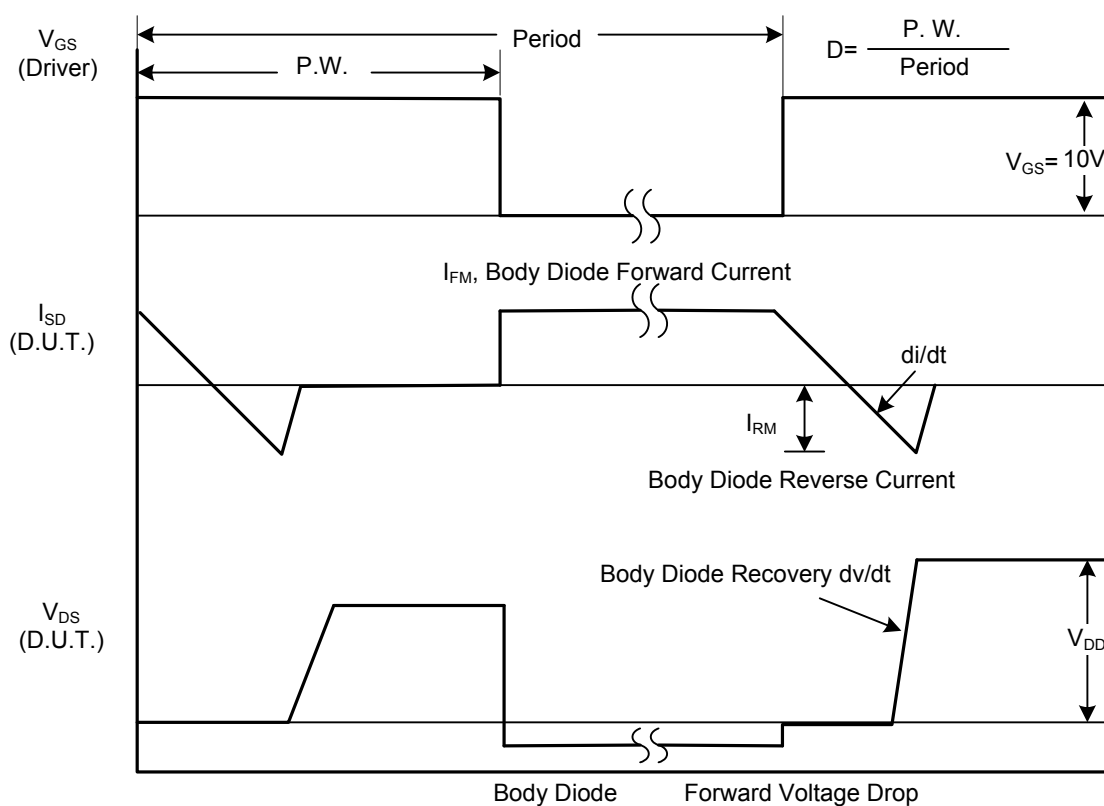


Fig. 1A Peak Diode Recovery dv/dt Test Circuit



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